

**AMENDMENT TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application.

1. (previously presented) A chuck system for supporting a semiconductor wafer, comprising:
  - a chuck platform for supporting the semiconductor wafer; and
  - a lift structure movably coupled with the chuck platform to receive the semiconductor wafer, including
    - a lift base, and
    - at least one lift pin removably coupled with the lift base, the lift pin having two ends with a first end removably coupled to the lift base and a second end for supporting the semiconductor wafer during lifting operation of the lift structure, wherein the first end of the lift pin is threaded and the lift base has a threaded hole for receiving the first end of the lift pin.
3. (original) The chuck system as claimed in claim 1 further comprising a bolt, wherein the first end of the lift pin is threaded and the bolt removably couples the lift pin with the lift base through an opening provided by the lift base.
4. (original) The chuck system as claimed in claim 1, wherein the lift structure comprises a plurality of lift pins coupled to the lift base.

5. (original) The chuck system as claimed in claim 1, wherein the lift pin is made of a conductive material.

6. (original) The chuck system as claimed in claim 1, wherein the chuck system is an electrostatic chuck system.

7. (original) The chuck system as claimed in claim 1, wherein the lift pin is conductively coupled to an electrically grounded end when the lift structure moves to lift the semiconductor wafer away from the chuck platform.

8. (original) The chuck system as claimed in claim 1, wherein the lift pin is conductively coupled to an electrically grounded end when the lift structure receives the semiconductor wafer to place the wafer on the chuck platform.

9. (original) The chuck system as claimed in claim 1, wherein the lift base is substantially flat and provides a least one opening for receiving the at least one lift pin.

10-16. (cancelled)

17. (currently amended) A method of maintaining a lift structure of a chuck system that supports a semiconductor wafer, comprising:

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providing a removable first lift pin to a lift base in the lift structure, wherein a first end of the first lift pin is threaded and the lift base has a threaded hole for receiving the first end of the first lift pin;

removing the first lift pin from the lift base with the lift structure being coupled to the chuck system; and

mounting a second lift pin to the lift base with the lift structure being coupled to the chuck system.

18. (original) The method of maintaining the lift structure as claimed in claim 17, wherein the first lift pin is removed from and the second lift pin is mounted to a same lift base with the same lift base being coupled to the lift structure.

19. (previously presented) The chuck system as claimed in claim 1, further comprising a driving mechanism for driving the lift structure, wherein the lift base of the lift structure includes at least one mounting hole for mounting the lift structure to the driving mechanism, and wherein the mounting hole is positioned closer to the center of the lift base than the lift pin.